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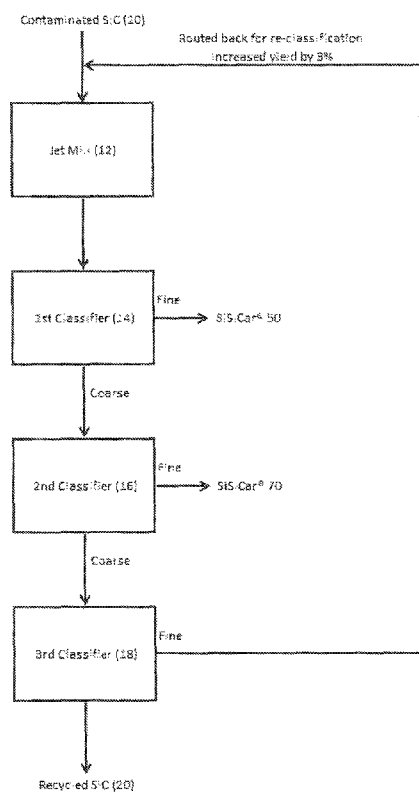
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(54) **Title:** METHOD AND SYSTEM FOR CLEANING CONTAMINATED SILICON CARBIDE PARTICLES

FIG. 1



(57) **Abstract:** The invention relates to a method and a system for cleaning contaminated silicon carbide (SiC) particles, and in particular, the contaminated SiC particles are cleaned by removing fine grain particles adhering to the contaminated SiC particles after being used in suspension in a cutting medium for the cutting or sawing of silicon wafers for solar cells and electronic objects often called spent sawing sludge.

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